



Click [here](#) for the 3D model.

Dimensions

Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
T	1.4mm +/-0.15mm
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

General Information

Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
Termination	Lead (SnPb)
Marking	No
AEC-Q200	No
Component Weight	300 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	51 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	10000 VDC
Dielectric Withstanding Voltage	12000 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms